





#### 100V PNP LED DRIVING TRANSISTOR IN SOT223

#### **Features**

- BV<sub>CEO</sub> > -100V
- Maximum continuous current I<sub>C</sub> = -1A
- $h_{FE} > 100 @ I_C = -150 mA, V_{CE} = -0.2 V$
- Lead Free, RoHS Compliant (Note 1)
- Halogen and Antimony Free "Green" Device (Note 2)
- Qualified to AEC-Q101 Standards for High Reliability

## Applications

LED TV backlight

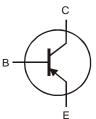
#### **Mechanical Data**

- Case: SOT223
- Case material: Molded Plastic. "Green" Molding Compound. UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish
- Weight: 0.112 grams (Approximate)

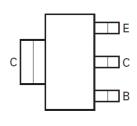
#### SOT223



Top View



Device Symbol



Top View Pin-Out

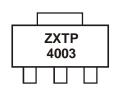
## **Ordering Information**

| Product     | Marking  | Reel size (inches) | Tape width (mm) | Quantity per reel |
|-------------|----------|--------------------|-----------------|-------------------|
| ZXTP4003GTA | ZXTP4003 | 7                  | 12              | 1,000             |

Notes:

- 1. No purposefully added lead.
- 2. "Green" devices, Halogen and Antimony Free, Diodes Inc's "Green" Policy can be found on our website at http://www.diodes.com

#### **Marking Information**



ZXTP4003 = Product type Marking Code



# Maximum Ratings @TA = 25°C unless otherwise specified

| Characteristic               | Symbol           | Value | Unit |
|------------------------------|------------------|-------|------|
| Collector-Base Voltage       | $V_{CBO}$        | -100  | V    |
| Collector-Emitter Voltage    | V <sub>CEO</sub> | -100  | V    |
| Emitter-Base Voltage         | $V_{EBO}$        | -7    | V    |
| Continuous Collector Current | lc               | -1    | А    |
| Peak Pulse Current (Note 4)  | I <sub>CM</sub>  | -3    | Α    |
| Base Current                 | Ι <sub>Β</sub>   | -500  | mA   |

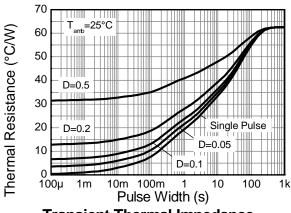
## Thermal Characteristics @TA = 25°C unless otherwise specified

| Characteristic                                   | Symbol           | Value       | Unit |
|--|------------------|-------------|------|
| Power Dissipation (Note 3)                       | $P_{D}$          | 2           | W    |
| Thermal Resistance, Junction to Ambient (Note 3) | R <sub>θJA</sub> | 62.5        | °C/W |
| Thermal Resistance, Junction to Leads (Note 5)   | $R_{	heta JL}$   | 28.75       | °C/W |
| Operating and Storage Temperature Range          | $T_{J_1}T_{STG}$ | -55 to +150 | °C   |

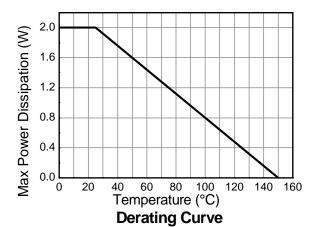
Notes:

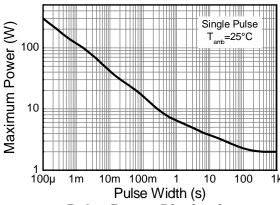
- 3. For a device surface mounted on 25mm X 25mm FR4 PCB with high coverage of single sided 1 oz copper, in still air conditions
- Measured under pulsed conditions. Pulse width = 300μs. Duty cycle ≤ 2%.
- 5. Thermal resistance from junction to solder-point (on the exposed collector pad).

## **Thermal Characteristics and Derating Information**



**Transient Thermal Impedance** 





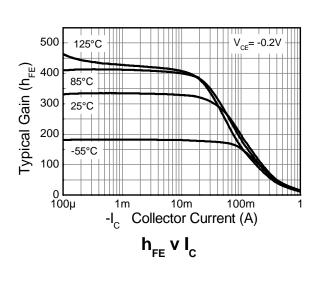


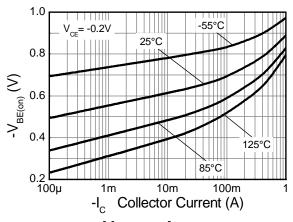
## Electrical Characteristics @T<sub>A</sub> = 25°C unless otherwise specified

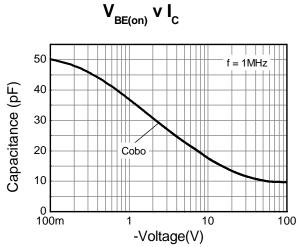
| Characteristic                                 | Symbol              | Min       | Тур        | Max   | Unit | Test Condition   |
|--|---------------------|-----------|------------|-------|------|--|
| Collector-Emitter Breakdown Voltage (Note 6)   | BV <sub>CEO</sub>   | -100      | -170       | -     | V    | I <sub>C</sub> = -10mA   |
| Collector Cut-off Current                      | I <sub>CBO</sub>    | -         | -          | -50   | nA   | V <sub>CB</sub> = -100V  |
| Emitter Cut-off Current                        | I <sub>EBO</sub>    | -         | -          | -50   | nA   | V <sub>EB</sub> = -7V  |
| Static Forward Current Transfer Ratio (Note 6) | h <sub>FE</sub>     | 60<br>100 | 133<br>112 | -     | -    | $I_C = -85$ mA, $V_{CE} = -0.15$ V<br>$I_C = -150$ mA, $V_{CE} = -0.2$ V |
| Base-Emitter Turn-On Voltage (Note 6)          | V <sub>BE(on)</sub> | -         | -0.71      | -0.95 | V    | I <sub>C</sub> = -150mA, V <sub>CE</sub> = -0.2V                         |
| Delay Time                                     | t <sub>(d)</sub>    | -         | 378        | -     | ns   |  |
| Rise Time                                      | t <sub>(r)</sub>    | -         | 388        | -     | ns   | $V_{CC} = -80V, I_{C} = -150mA,$   |
| Storage Time                                   | t <sub>(s)</sub>    | -         | 1348       | -     | ns   | $-I_{B2} = 1.5 \text{mA}, V_{CE(ON)} = -0.2 \text{V}$                    |
| Fall Time                                      | t <sub>(f)</sub>    | -         | 382        | -     | ns   |  |
| Storage Time                                   | t <sub>(s)</sub>    | -         | 75         | -     | ns   | $V_{CC} = -80V, I_{C} = -150mA,$   |
| Fall Time                                      | t <sub>(f)</sub>    | -         | 363        | -     | ns   | $-I_{B2} = 1.5 \text{mA}, V_{CE(ON)} = -4 \text{V}$                      |

Notes: 6. Measured under pulsed conditions. Pulse width =  $300\mu s$ . Duty cycle  $\leq 2\%$ 

## Electrical Characteristics @TA = 25°C unless otherwise specified



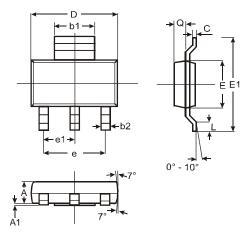




Capacitance v Voltage

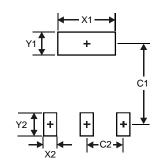


# **Package Outline Dimensions**



| SOT223               |       |      |      |  |  |
|----------------------|-------|------|------|--|--|
| Dim                  | Min   | Max  | Тур  |  |  |
| Α                    | 1.55  | 1.65 | 1.60 |  |  |
| A1                   | 0.010 | 0.15 | 0.05 |  |  |
| b1                   | 2.90  | 3.10 | 3.00 |  |  |
| b2                   | 0.60  | 0.80 | 0.70 |  |  |
| С                    | 0.20  | 0.30 | 0.25 |  |  |
| D                    | 6.45  | 6.55 | 6.50 |  |  |
| Е                    | 3.45  | 3.55 | 3.50 |  |  |
| E1                   | 6.90  | 7.10 | 7.00 |  |  |
| е                    | _     | _    | 4.60 |  |  |
| e1                   |       | _    | 2.30 |  |  |
| L                    | 0.85  | 1.05 | 0.95 |  |  |
| q                    | 0.84  | 0.94 | 0.89 |  |  |
| All Dimensions in mm |       |      |      |  |  |

# **Suggested Pad Layout**



| Dimensions | Value (in mm) |  |  |
|------------|---------------|--|--|
| X1         | 3.3           |  |  |
| X2         | 1.2           |  |  |
| Y1         | 1.6           |  |  |
| Y2         | 1.6           |  |  |
| C1         | 6.4           |  |  |
| C2         | 2.3           |  |  |





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